

Phosphorus-Containing Flame-Retardant Hardeners, Epoxy Resins,
Advanced Epoxy Resins and Cured Epoxy Resins

Field of the Invention

5 The present invention relates generally to an active-hydrogen-
containing phosphorus compound for cross-linking a resin and for
imparting flame-retardancy to the cured resin, and in particular to a cured
frame-retardant epoxy resin prepared by reacting the hardener with a di- or
poly-functional epoxy resin via an addition reaction between the active
10 hydrogen and the epoxide group. It also relates to an epoxy resin made
from the active-hydrogen-containing phosphorus compound and
epihalohydrin.

Background of the Invention

15 Typical hardeners for epoxy resins and advanced epoxy resins are
phenol-formaldehyde novolac resin, dicyandiamide, methylenedianiline,
diaminodiphenyl sulfone, phthalic anhydride, and hexahydrophthalic
anhydride, etc. The advanced epoxy resins and cured epoxy resins
prepared with these hardeners do not have flame retardancy, and thus can
20 not meet the safety requirements.

Several approaches for modification of epoxy backbone for enhancing
the thermal properties of epoxy resins have been reported. Aromatic
bromine compounds in conjunction with antimony oxide are widely used as
a flame retardant for epoxy resins. Tetrabromobisphenol A is a typical

3989531 (1976); 4058507 (1997); 4104257 (1978); 4170711 (1979); and 4647648(1987)].

Although the tetrabromobisphenol A-containing advanced epoxy resin shows flame retardant property, major problems encountered with this
5 system are concerned with the generation of toxic and corrosive fumes during combustion such as dioxin and benzofuran.

The flame retardant having a small molecular weight tends to lower the mechanical properties of the epoxy resins, and migrate/vaporize from the epoxy resins such that the flame retardancy thereof diminishes.

10 It is an object of this invention to provide a phosphorus-containing flame retardant hardener for cross-linking a resin and for imparting flame-retardancy to the cured resin.

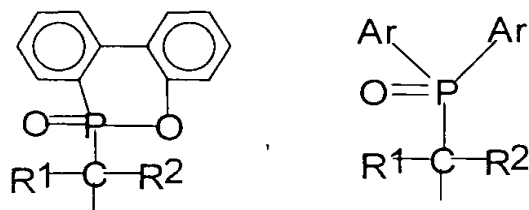
It is another object of this invention to provide advanced epoxy resins and cured epoxy resins with good thermal stability, superior heat resistance,
15 and without environmental problem, which are suitable for use in making printed circuit boards and in semiconductor encapsulation applications.

It is also an object of this invention to provide phosphorus-containing flame-retardant epoxy resins which are suitable for use in making printed circuit boards and in semiconductor encapsulation applications.

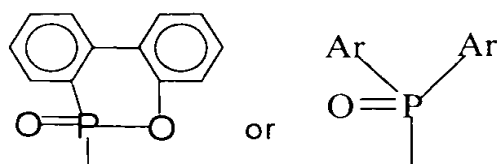
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Summary of the Invention

In order to accomplish the aforesaid objects, a flame-retardant hardener containing one of the following phosphorus-containing rigid groups was synthesized in the present invention:



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- 10 wherein R¹ and R² independently are H, C1~C18 alkyl, C6~C18 aryl, C6~C18 substituted aryl, C6~C18 aryl methylene, or C6~C18 substituted aryl methylene; and Ar is an un-substituted or substituted phenyl or phenoxy radical. The hardener of the present invention is prepared by bounding the phosphorus-containing rigid group to bisphenol-A (BPA),
- 15 diamonodiphenyl methane (DDM), diaminodiphenyl sulfone (DDS), melamine (MA) or dicyandiamide (DICY). The phosphorus-containing bisphenol-A of the hardeners of the present invention can be reacted with an excess amount of epoxy resin to prepare a flame-retardant advanced epoxy, which is suitable for use in making printed circuit boards.

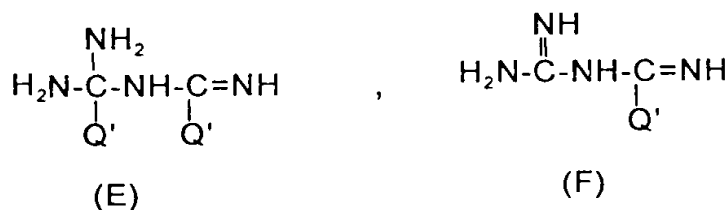
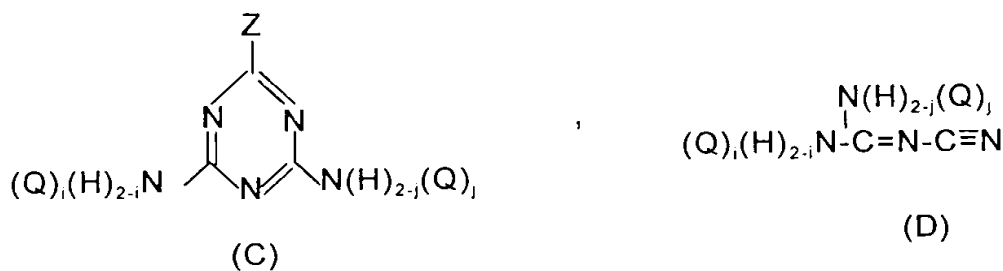
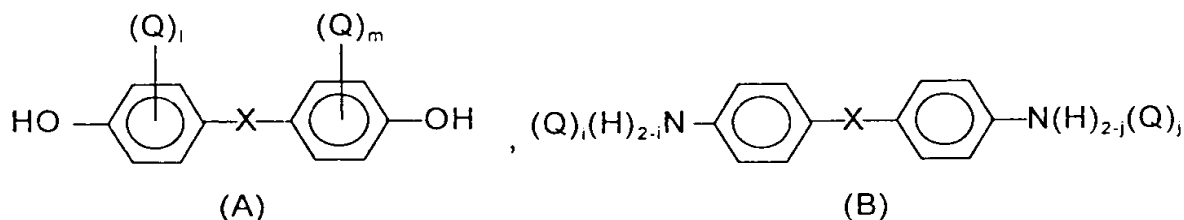
- 20 The present invention also provides a flame-retardant epoxy resin by reacting the hardener of the present invention with an excess of epihalohydrin in the presence of an alkali metal hydroxide.

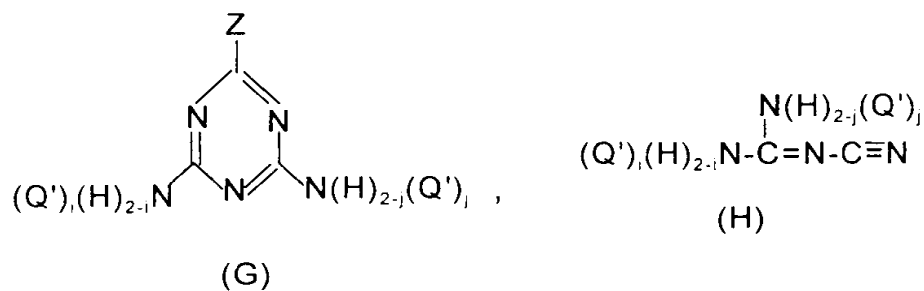
The present invention also provides a cured flame-retardant epoxy resin by using the hardener of the present invention and a cured flame-

retardant epoxy resin from the flame-retardant epoxy resin of the present invention. The cured flame-retardant epoxy resins so prepared have a high glass transition temperature (T_g), high decomposition temperature and high elastic modulus, and are free of toxic and corrosive fumes during combustion, and thus are suitable for printed circuit board and semiconductor encapsulation applications.

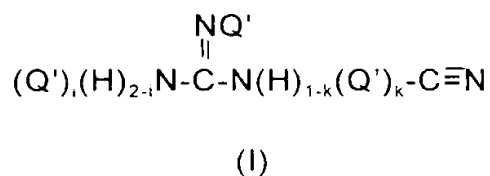
Detailed Description of the Invention

A phosphorus-containing compound prepared in accordance with the present invention has a formula selecting from the group consisting of (A) to (I):





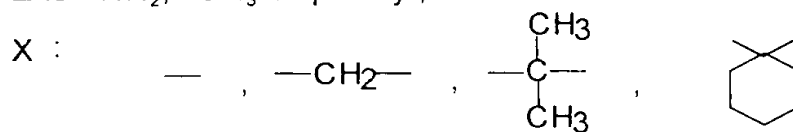
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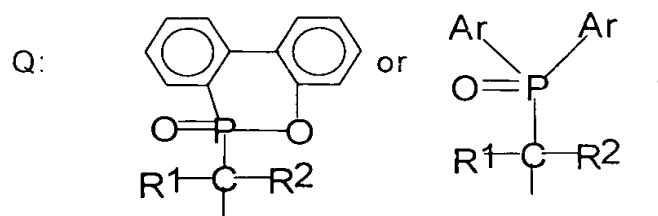
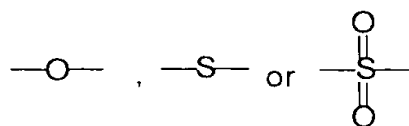
wherein

10 I and m independently are 0, 1 or 2, and $I + m > 0$; i and j independently are 0, 1 or 2, and $0 < i + j < 4$; k is 0 or 1, and $i + k < 3$;

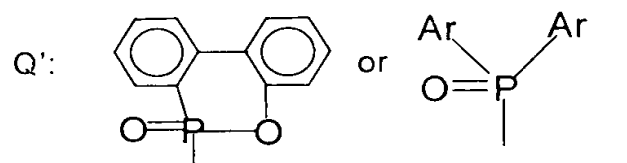
Z is $-\text{NH}_2$, $-\text{CH}_3$ or phenyl;



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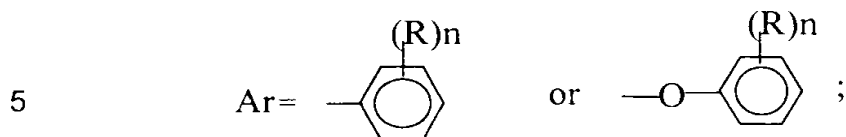


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wherein

R¹, R² independently are H, C1~C18 alkyl, C6~C18 aryl, C6~C18 substituted aryl, C6~C18 aryl methylene, or C6~C18 substituted aryl methylene;



wherein R is C1-C4 alkyl or C6-C18 aryl; and n is an integer of 0 to 5.

Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (A).

10 Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (B).

Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (C).

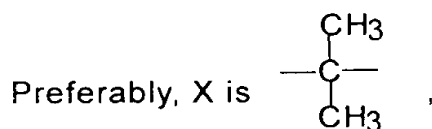
15 Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (D).

Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (E) or (F).

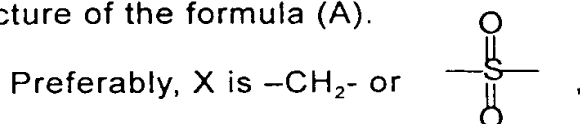
Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (G).

20 Preferably, the phosphorus-containing compound of the present invention has a structure of the formula (H) or (I).

Preferably, R¹ and R² are hydrogen. Preferably, n is 0.



when the phosphorus-containing compound of the present invention has a structure of the formula (A).



when the phosphorus-containing compound of the present invention has a structure of the formula (B).

Preferably, Ar is phenoxy, when the phosphorus-containing compound of the present invention has a structure of one of the formulas (A) to (D).

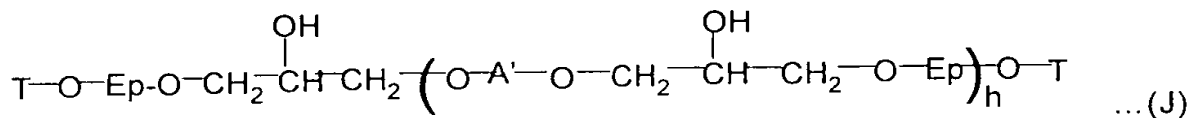
Preferably, Ar is phenyl, when the phosphorus-containing compound of the present invention has a structure of one of the formulas (F) to (I).

Preferably, i and j are 0 or 1.

Preferably, Z is $-\text{NH}_2$.

Preferably, k is 0.

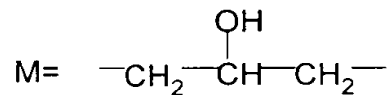
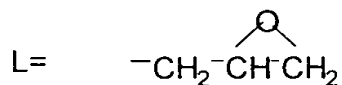
The present invention also discloses a phosphorus-containing frame-retardant advanced epoxy resin and cured epoxy resin having the following formula (J):



wherein

$0 < h < 10$;

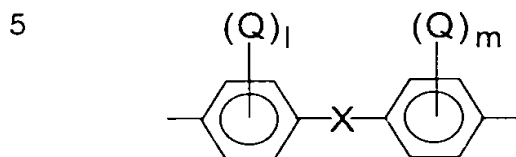
T = L or M, wherein



the formula (J) represents the advanced epoxy resin, when $T = L$; and

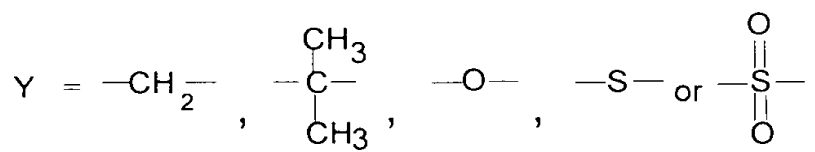
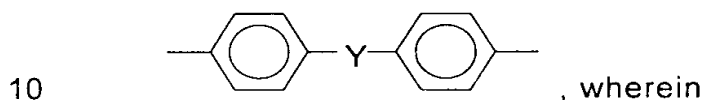
the formula (J) represents the cured epoxy resin, when $T = M$;

A' is



wherein Q, X, l and m are defined as above; and

Ep is



or a phenol-aldehyde novolac epoxy resin backbone, and when Ep is

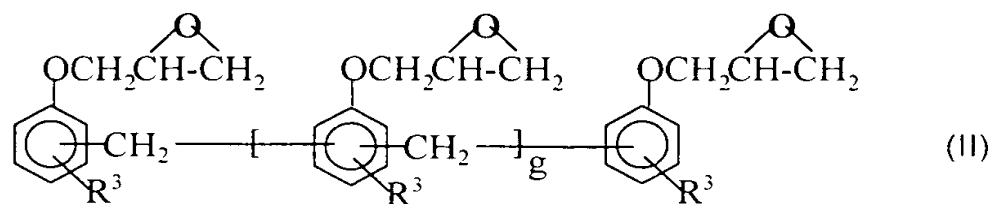
the phenol-aldehyde novolac epoxy resin backbone, the flame-

retardant advanced epoxy resin and the cured epoxy resin

15 represented by the formula (J) is prepared by reacting the

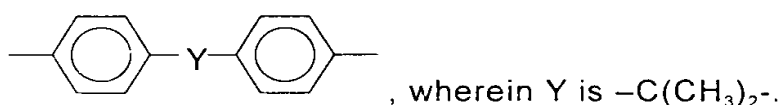
phosphorus-containing compound (A) with a phenol-aldehyde

novolac epoxy resin having the following formula (II)



5 wherein R^3 is hydrogen, or $-\text{CH}_3$, and g is an integer of 1-6.

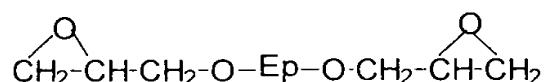
Preferably, Ep in the formula (J) is



Preferably, Ep in the formula (J) is the phenol-aldehyde novolac epoxy resin backbone, wherein R^3 in the phenol-aldehyde novolac epoxy resin (II)

10 is $-\text{CH}_3$.

A suitable process for preparing the flame-retardant advanced epoxy resin (J) comprises reacting the phosphorus-containing compound (A) with an excess amount of an epoxy resin having the following formula:



15 wherein Ep is defined as above.

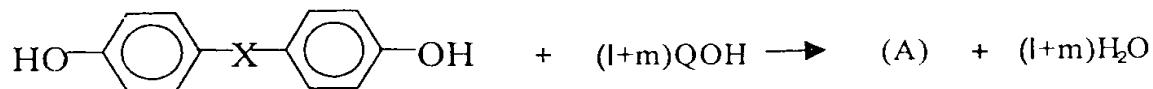
The phosphorus-containing compounds (A) to (I) of the present invention can be used as a flame-retardant hardener for an epoxy resin, when there is more than one active hydrogen contained therein; and can be used as a flame retardant for the epoxy resin, if there is only one active

20 hydrogen contained therein.

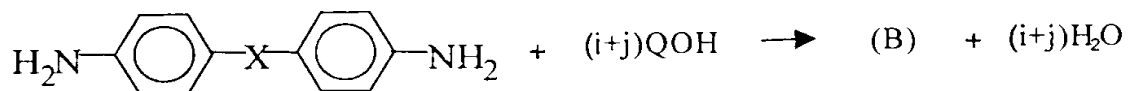
Suitable processes for preparing the phosphorus-containing compounds (A)-(I) of the present invention include (but not limited)

processes utilizing the following reactions:

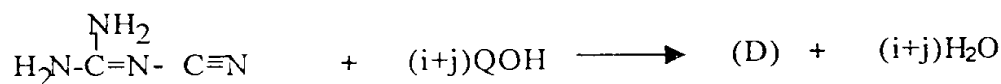
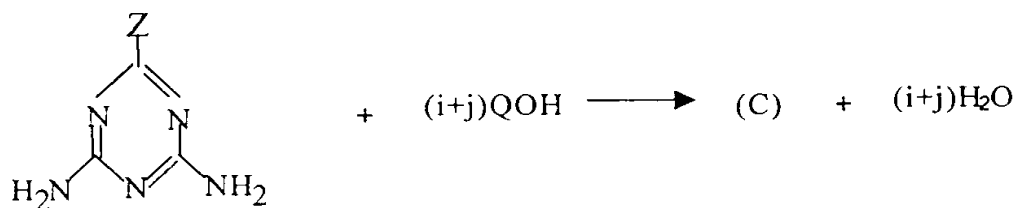
Compounds (A)-(D): Substituted BPA, DDM, DDS, MA and DICY types



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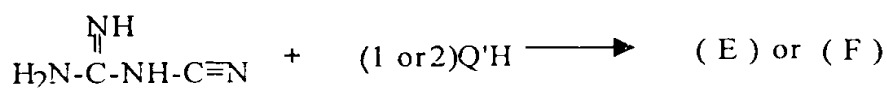


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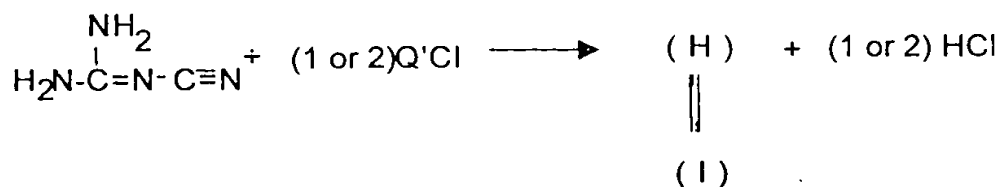
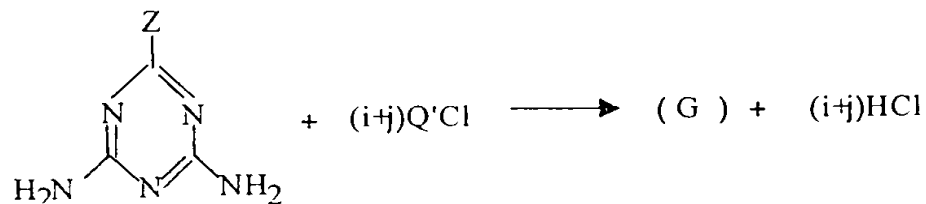
Compounds (E) and (F): Dicyandiamide addition product types

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Compounds (G)-(I): Substituted melamine and dicyandiamide types

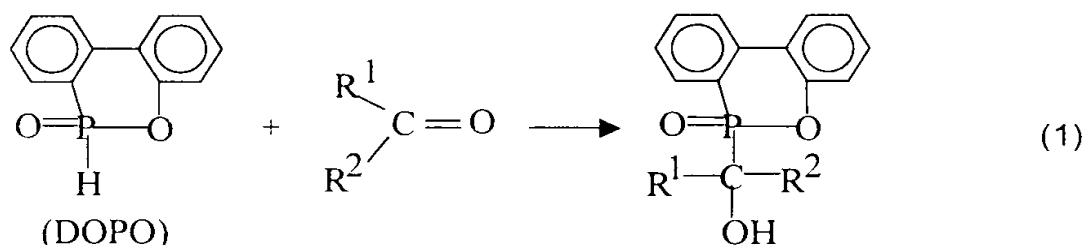
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l, m, i, j, k, Z, X, Q and Q' in the aforesaid reactions for synthesizing the phosphorus-containing compounds (A)-(I) are defined as above.

The QOH reactant used in the aforesaid reactions for synthesizing the phosphorus-containing compounds (A)-(D) may be prepared by the

5 following reactions (1) and (2):



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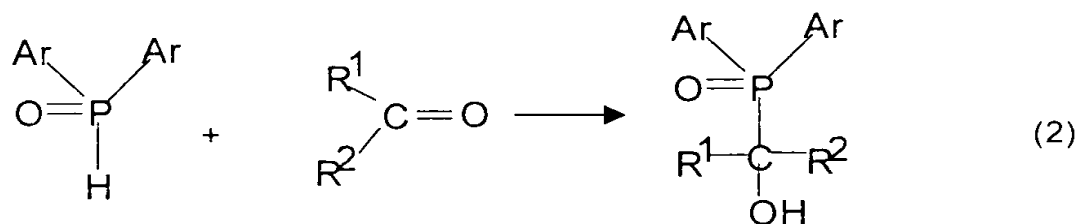
wherein DOPO is an abbreviation of 9,10-dihydro-9-oxa-10-

phosphaphenanthrene 10-oxide, R¹ and R² are defined as above. 2-(6-

Oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl) methanol (abbreviated as

ODOPM) can be synthesized when R¹ and R² in the reaction (1) are both

15 hydrogen.



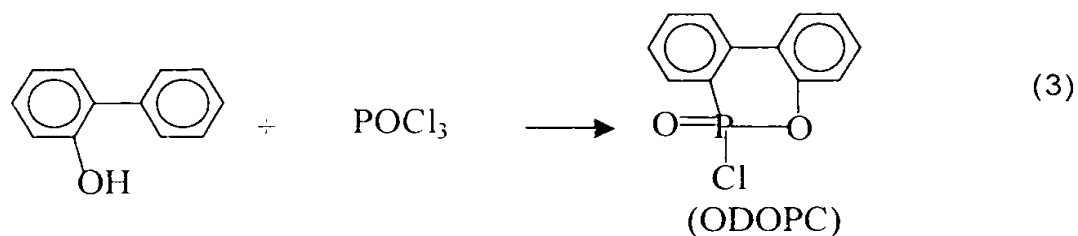
20 R¹, R² and Ar in the reaction (2) are defined as above. Diphenoxy

phosphoryl methanol (abbreviated as DPOM) can be synthesized when R¹,

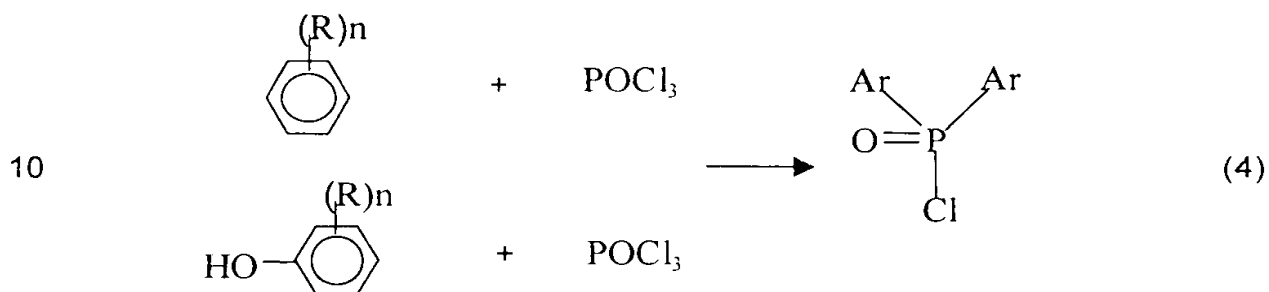
R² are both hydrogen, and Ar is phenoxy in the reaction (2).

The Q'Cl reactant used in the aforesaid reactions for synthesizing the phosphorus-containing compounds (G)-(I) may be prepared by the

following reactions (3) and (4):



wherein ODOPC in the reaction (3) is an abbreviation of 2-(6-oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl)chloride;



wherein R, n and Ar in the reaction (4) are defined as above. Diphenyl phosphoryl chloride (abbreviated as DPC) can be synthesized, when R is hydrogen and Ar is phenyl in the reaction (4).

The present invention further synthesized a phosphorus-containing flame-retardant cured epoxy resin by curing an epoxy resin or advanced epoxy resin with the hardener of the present invention alone or together with the conventional curing agent for the epoxy resin in a molten state.

20 The conventional curing agent for the epoxy resin preferably is selected from the group consisting of phenol-formaldehyde novolac resin, dicyandiamide, methylenedianiline, diaminodiphenyl sulfone, phthalic anhydride and hexahydrophthalic anhydride. Preferably, the curing reaction is carried out at a temperature higher than 150°C and with a

stoichiometric amount of the hardener and the curing agent, i.e. the equivalent ratio of the epoxide group in the epoxy resin and/or advance epoxy resin and the functional groups in the hardener and the curing agent is about 1:1. More preferably, the curing reaction is carried out in the presence of a curing promoter such as triphenylphosphine, and in an amount of 0.01-10.0 parts by weight of the curing promoter per 100 parts by weight of the epoxy resin and/or advance epoxy resin. The phosphorus-containing flame-retardant cured epoxy resin of the present invention is suitable for use in making a flame-retardant printed circuit board as a matrix resin and in semiconductor encapsulation.

Preferably, the phosphorus-containing flame-retardant cured epoxy resin of the present invention contains 0.5-30 wt%, and more preferably 0.5-5 wt%, of phosphorus.

A suitable epoxy resin for use in the present invention can be any known epoxy resin, for examples those having two epoxide groups such as bisphenol A epoxy resin, bisphenol F epoxy resin, bisphenol S epoxy resin and biphenol epoxy resin, and those having more than two epoxide groups such as phenol formaldehyde novolac epoxy and cresol formaldehyde novolac epoxy (CNE) with 4-18 functional groups, and mixtures thereof.

An advanced epoxy resin suitable for use in the present invention can be prepared by conducting a curing reaction of the conventional curing agent for an epoxy resin and using an excess amount of an epoxy resin in a molten state.

Preparation of phosphorus-containing hardeners

i). Substituted bisphenol-A (BPA), diamonodiphenyl methane (DDM), diaminodiphenyl sulfone (DDS), melamine (MA) or dicyandiamide (DICY) types

5 Preparation Example 1-A (P-1-A, ODOPM-BPA-A):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (228 g) bisphenol-A (BPA) was added, heated to 170°C and then stirred to a molten state. 0.7 g (0.3 wt%) potassium acetate was mixed with the molten BPA followed by adding slowly 1 mole (246 g) 2-(6-oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl) methanol (ODOPM). The mixture was heated gradually to a temperature of 220°C when the addition of ODOPM was completed. The substitution reaction was continued for 6 hours. The reaction product was dissolved in 15 cyclohexanone, and washed with water several times before the solvent was evaporated under vacuum to obtain ODOPM-BPA-A (P-1-A). Yield, 98%; softening temperature, 125-132°C. Phosphorus content: 6.79%.

Preparation Example 1-B (P-1-B, ODOPM-BPA-A):

20 To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (228 g) bisphenol-A (BPA) was added, heated to 170°C and then stirred to a molten state. 1.14 g (0.5 wt%) potassium acetate was mixed with the molten BPA followed by adding slowly 1.5 mole

(369 g) ODOPM. The mixture was heated gradually to a temperature of 220°C when the addition of ODOPM was completed. The substitution reaction was continued for 8 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before the solvent
5 was evaporated under vacuum to obtain ODOPM-BPA-B (P-1-B). Yield, 96%; softening temperature, 136-140°C. Phosphorus content: 8.16%.

Preparation Example 1-C (P-1-C, ODOPM-BPA-A):

To an one liter four-inlet flask equipped with a thermocouple and
10 temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (228 g) bisphenol-A (BPA) was added, heated to 170°C and then stirred to a molten state. 1.14 g (0.5 wt%) potassium acetate was mixed with the molten BPA followed by adding slowly 2 mole (492 g) ODOPM. The mixture was heated gradually to a temperature of
15 220°C when the addition of ODOPM was completed. The substitution reaction was continued for 10 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before the solvent was evaporated under vacuum to obtain ODOPM-BPA-C (P-1-C). Yield, 92%; softening temperature, 143-148°C. Phosphorus content: 9.06%.

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Preparation Example 2 (P-2, DPOM-BPA):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (228 g) bisphenol-A (BPA) was added, heated to

170°C and then stirred to a molten state. 0.7 g (0.3 wt%) potassium acetate was mixed with the molten BPA followed by adding slowly 1 mole (264 g) diphenoxy phosphoryl methanol (DPOM). The mixture was heated gradually to a temperature of 220°C when the addition of DPOM was completed. The substitution reaction was continued for 8 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before the solvent was evaporated under vacuum to obtain DPOM-BPA (P-2). Yield, 98%; softening temperature, 118-124°C. Phosphorus content: 6.54%.

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Preparation Example 3 (P-3, ODOPM-DDM):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (198 g) diaminodiphenylmethane (DDM) was added, heated to 170°C and then stirred to a molten state. 0.7 g (0.3 wt%) potassium acetate was mixed with the molten DDM followed by adding slowly 1 mole (246 g) ODOPM. The mixture was heated gradually to a temperature of 220°C when the addition of ODOPM was completed. The substitution reaction was continued for 8 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before the solvent was evaporated under vacuum to obtain ODOPM-DDM (P-3). Yield, 98%; softening temperature, 145-149°C. Phosphorus content: 6.57%.

20

Preparation Example 4 (P-4, DPOM-DDM):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (198 g) diaminodiphenylmethane (DDM) was added, heated to 170°C and then stirred to a molten state. 0.7 g (0.3 wt%) potassium acetate was mixed with the molten DDM followed by adding slowly 1 mole (264 g) DPOM. The mixture was heated gradually to a temperature of 220°C when the addition of DPOM was completed. The substitution reaction was continued for 8 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before the solvent was evaporated under vacuum to obtain DPOM-DDM (P-4). Yield, 98%; softening temperature, 136-141°C. Phosphorus content: 6.31%.

Preparation Example 5 (P-5, ODOPM-DDS):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (248 g) diaminodiphenyl sulfone (DDS) was added, heated to 180°C and then stirred to a molten state. 0.7 g (0.3 wt%) potassium acetate was mixed with the molten DDS followed by adding slowly 1 mole (246 g) ODOPM. The mixture was heated gradually to a temperature of 220°C when the addition of ODOPM was completed. The substitution reaction was continued for 8 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before

the solvent was evaporated under vacuum to obtain ODOPM-DDS (P-5).

Yield, 92%; softening temperature, 147-152°C. Phosphorus content:

5.88%.

5 Preparation Example 6 (P-6, DPOM-DDS):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (248 g) diaminodiphenyl sulfone (DDS) was added, heated to 180°C and then stirred to a molten state. 0.7 g (0.3 wt%)

10 potassium acetate was mixed with the molten DDS followed by adding slowly 1 mole (264 g) DPOM. The mixture was heated gradually to a temperature of 220°C when the addition of DPOM was completed. The substitution reaction was continued for 8 hours. The reaction product was dissolved in cyclohexanone, and washed with water several times before

15 the solvent was evaporated under vacuum to obtain DPOM-DDS (P-6).

Yield, 92%; softening temperature, 141-146°C. Phosphorus content:

6.28%.

Preparation Example 7 (P-7, ODOPM-MA):

20 To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (126 g) Melamine (MA) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 90°C and then stirred until MA was dissolved completely. 0.63 g potassium acetate was mixed

with the resulting solution followed by adding slowly 1 mole (246 g) ODOPM. The mixture was heated gradually to a temperature of 168°C when the addition of ODOPM was completed. The substitution reaction was continued for 8 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain ODOPM-MA (P-7). Yield, 98%; softening temperature, 129-134°C. Phosphorus content: 8.76%. Nitrogen content: 23.73%.

Preparation Example 8 (P-8, DPOM-MA):

10 To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (126 g) Melamine (MA) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 90°C and then stirred until MA was dissolved completely. 0.63 g potassium acetate was mixed
15 with the resulting solution followed by adding slowly 1 mole (264 g) DPOM. The mixture was heated gradually to a temperature of 168°C when the addition of DPOM was completed. The substitution reaction was continued for 8 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain DPOM-MA (P-8). Yield, 98%;
20 softening temperature, 124-130°C. Phosphorus content: 8.33%. Nitrogen content: 22.58%.

Preparation Example 9 (P-9, ODOPM-DICY):

To an one liter four-inlet flask equipped with a thermocouple and

temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (86 g) dicyandiamide (DICY) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 90°C and then stirred until DICY was dissolved completely. 0.6 g potassium acetate was mixed
5 with the resulting solution followed by adding slowly 1 mole (246 g) ODOPM. The mixture was heated gradually to a temperature of 168°C when the addition of ODOPM was completed. The substitution reaction was continued for 8 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain ODOPM-DICY (P-9). Yield,
10 98%; softening temperature, 138-143°C. Phosphorus content: 9.87%. Nitrogen content: 17.83%.

Preparation Example 10 (P-10, DPOM-DICY):

To an one liter four-inlet flask equipped with a thermocouple and
15 temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (86 g) dicyandiamide (DICY) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 90°C and then stirred until DICY was dissolved completely. 0.6 g potassium acetate was mixed with the resulting solution followed by adding slowly 1 mole (264 g) DPOM.
20 The mixture was heated gradually to a temperature of 168°C when the addition of DPOM was completed. The substitution reaction was continued for 8 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain DPOM-DICY (P-10). Yield, 98%; softening temperature, 129-135°C. Phosphorus content: 9.34%.

Nitrogen content: 16.87%.

ii). Dicyandiamide addition product type

Preparation Example 11 (P-11, DOPO-DICY):

5 To an one liter four-inlet flask equipped with a thermocouple and
temperature controller, a reflux condenser, a nitrogen feed and a
mechanical stirrer, 1 mole (86 g) dicyandiamide (DICY) was added, heated
to 120°C and then stirred to a molten state. 1 mole (216 g) 9,10-dihydro-
9-oxa-10-phosphaphenanthrene-10-oxide (DOPO) was added slowly to the
10 molten DICY, and the resulting mixture was heated gradually to a
temperature of 190°C when the addition of DOPO was completed. The
addition reaction was continued for 4 hours. The reaction mixture was
cooled to obtain DOPO-DICY (P-11). Yield, 96%; softening temperature,
137-143°C. Phosphorus content: 10.26%. Nitrogen content: 18.54%.

15

Preparation Example 12 (P-12, DPP-DICY):

To an one liter four-inlet flask equipped with a thermocouple and
temperature controller, a reflux condenser, a nitrogen feed and a
mechanical stirrer, 1 mole (86 g) dicyandiamide (DICY) was added, heated
20 to 120°C and then stirred to a molten state. 1 mole (234 g) diphenyl
phosphite (DPP) was added slowly to the molten DICY, and the resulting
mixture was heated gradually to a temperature of 190°C when the addition
of DPP was completed. The addition reaction was continued for 4 hours.
The reaction mixture was cooled to obtain DPP-DICY (P-12). Yield, 96%;

softening temperature, 134-138°C. Phosphorus content: 9.68%.

Nitrogen content: 17.50%.

iii). Substituted melamine and dicyandiamide types

5 Preparation Example 13 (P-13, ODOPC-MA):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (126 g) Melamine (MA) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 120°C and then stirred
10 until MA was dissolved completely. 1 mole (251 g) 2-(6-oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl)chloride (ODOPC) was added slowly to the resulting solution. The mixture was heated gradually to a temperature of 170°C when the addition of ODOPC was completed. The reaction was continued for 16 hours. The reaction mixture was cooled
15 and filtered, and the resulting cake was dried to obtain ODOPC-MA (P-13). Yield, 94%; softening temperature, 137-142°C. Phosphorus content: 9.10%. Nitrogen content: 24.67%.

Preparation Example 14 (P-14, DPC-MA):

20 To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (126 g) Melamine (MA) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 120°C and then stirred until MA was dissolved completely. 1 mole (253 g) diphenyl phosphoryl

chloride (DPC) was added slowly to the resulting solution. The mixture was heated gradually to a temperature of 168°C when the addition of DPC was completed. The reaction was continued for 10 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain
5 DPC-MA (P-14). Molecular weight: 558. Yield, 94%; softening temperature, 131-135°C. Phosphorus content: 9.05%. Nitrogen content: 24.53%.

Preparation Example 15 (P-15, ODOPC-DICY):

10 To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a mechanical stirrer, 1 mole (86 g) dicyandiamide (DICY) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 120°C and then stirred until DICY was dissolved completely. 1 mole (251 g) ODOPC was added
15 slowly to the resulting solution. The mixture was heated gradually to a temperature of 170°C when the addition of ODOPC was completed. The reaction was continued for 8 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain ODOPC-DICY (P-15). Molecular weight: 515. Yield, 96%; softening temperature, 134-139°C.
20 Phosphorus content: 10.32%. Nitrogen content: 18.64%.

Preparation Example 16 (P-16, DPC-DICY):

To an one liter four-inlet flask equipped with a thermocouple and temperature controller, a reflux condenser, a nitrogen feed and a

mechanical stirrer, 1 mole (86 g) dicyandiamide (DICY) and 500 ml N,N-dimethylacetamide (DMAc) were added, heated to 120°C and then stirred until DICY was dissolved completely. 1 mole (253 g) DPC was added slowly to the resulting solution. The mixture was heated gradually to a
5 temperature of 170°C when the addition of DPC was completed. The reaction was continued for 8 hours. The reaction mixture was cooled and filtered, and the resulting cake was dried to obtain DPC-DICY (P-16).
Molecular weight: 519. Yield, 96%; softening temperature, 127-132°C. Phosphorus content: 10.25%. Nitrogen content: 18.51%.

10

Preparation of phosphorus-containing advanced epoxy resins and cured epoxy resins

i). An advanced epoxy resin prepared from bisphenol A epoxy resin and ODOPM-BPA

15 Example A (P-A):

To a one liter reactor equipped with a temperature controller, a reflux condenser, a nitrogen feed, a vacuum system and a mechanical stirrer, 564 g diglycidyl ether of bisphenol A (BPA epoxy resin) having an epoxide equivalent weight (EEW) of 188 was added, and heated to 110°C while
20 stirring and vacuuming (<100 mmHg) for a period of 30 minutes to remove a trace amount of water contained in the epoxy resin. The vacuuming was stopped, and dried nitrogen was introduced into the reactor until the atmospheric pressure was reached. The temperature of the reactor was raised to 130°C, and 228 g ODOPM-BPA-A (P-1-A) was then added while

stirring. After a molten mixture of ODOPM-BPA-A and BPA epoxy resin was formed, 500 ppm (based on total weight) ethyl triphenyl phosphonium chloride was added, and the temperature of the reaction mixture was increased to 160°C and maintained at 160°C for two hours. The
5 equivalent ratio of epoxide group to hydroxyl group was 3.0:1 at the starting point of the reaction. The resultant advanced epoxy resin had an EEW of 396.

Example B (P-B):

10 The procedures of Example A were repeated except that ODOPM-BPA-A (P-1-A) was replaced by ODOPM-BPA-B (P-1-B). The equivalent ratio of epoxide group to hydroxyl group was 3.0:1 at the starting point of the reaction. The resultant solid advanced epoxy resin had an EEW of 424.

15

Example C (P-C):

The procedures of Example A were repeated except that ODOPM-BPA-A (P-1-A) was replaced by ODOPM-BPA-C (P-1-C). The equivalent ratio of epoxide group to hydroxyl group was 3.0:1 at the starting point of
20 the reaction. The resultant solid advanced epoxy resin had an EEW of 453.

Control Example A:

The procedures of Example A were repeated except that ODOPM-

BPA-A (P-1-A) was replaced by bisphenol A. The equivalent ratio of epoxide group to hydroxyl group was 2.04:1 at the starting point of the reaction. The resultant solid advanced epoxy resin (designated as Control) had an EEW of 483.

5

Control Example B:

The procedures of Example A were repeated except that ODOPM-BPA-A (P-1-A) was replaced by tetrabromobisphenol A. The equivalent ratio of epoxide group to hydroxyl group was 2.58:1 at the starting point of the reaction. The resultant solid advanced epoxy resin (designated as TBBA) had an EEW of 483.

10

Control Example C:

The procedures of Example A were repeated except that ODOPM-BPA-A (P-1-A) was replaced by bis(3-hydroxyphenyl) phenyl phosphate (BHPP). The equivalent ratio of epoxide group to hydroxyl group was 2.04:1 at the starting point of the reaction. The resultant solid advanced epoxy resin (designated as BHPP) had an EEW of 483.

15

20 ii). Preparation of a cured epoxy resin from an advanced epoxy resin

Cured epoxy resins were prepared from the advanced epoxy resins prepared in Examples A-C and Control Examples A-C with a curing agent selected from phenol-formaldehyde novolac resin (PN), melamine-phenol-formaldehyde-novolac resin (MPN) and dicyandiamide (DICY).

The advanced epoxy resin was mixed with the curing agent (1:1 equivalent ratio) at 150°C with stirring, and the well mixed molten mixture was poured into a hot aluminum mould, cured in an oven at 175°C for one hour, and then postcured at 200°C for two hours.

- 5 The thermogravimetric analysis data of the resulting cured epoxy resins are shown in Table 1. The flame-retardant properties of the resulting cured epoxy resins are shown in Table 2.

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Table 1 TGA data

Specimens				Temperature of 5 wt% loss, °C		Temperature of 10 wt% loss, °C		Rapid rate Tr (°C)				Char yield at 700°C, (%)	
Advanced epoxy	Hardener	Content of P (%)	Tg (°C)	Air	N ₂	Air	N ₂	Step 1 Air	Step 1 N ₂	Step 2 Air	Step 2 N ₂	Air	N ₂
Control	PN	0	110	417	423	445	441	466	474	634	—	2	15
P-A	PN	1.54	131	387	387	417	413	455	452	674	—	17	24
P-B	PN	2.20	120	377	383	407	401	444	441	590	597	20	26
P-C	PN	2.96	115	367	367	397	393	452	438	622	614	22	27
Control	MPN	0	125	393	407	417	427	474	478	623	—	1	16
P-A	MPN	1.67	143	367	377	387	397	438	450	633	—	15	20
P-B	MPN	2.36	140	357	367	377	387	415	435	641	585	18	22
P-C	MPN	2.97	136	347	347	367	369	397	415	662	612	21	25
Control	DICY	0	132	393	393	417	417	478	481	628	658	2	6
P-A	DICY	1.86	150	367	377	387	387	433	441	627	676	12	16
P-B	DICY	2.61	140	357	363	377	387	429	419	621	692	15	19
P-C	DICY	3.26	137	347	353	363	367	390	407	614	674	17	21
BHPP	PN	4.27	105	345	347	361	361	380	376	532	530	35	37
TBBA	PN	17.72*	124	361	363	365	367	386	380	—	—	10	23

*Content of Br

-: Step 2 of rapid rate was not found

Table 2 Flame retardant properties (UL-94 test)

Specimens	Content of flame-retardant element (%)	Burning time (Sec)	Fume*	Drip	Classification
PN Control	P (0.00%)	89	--	Yes	V-2
P-A-PN	P (1.54%)	18	-- --	No	V-1
P-B-PN	P (2.20%)	0	-- --	No	V-0
P-C-PN	P (2.96%)	0	-- --	No	V-0
MPN Control	P/N (0.00/3.11%)	36	+	No	V-2
P-A-MPN	P/N (1.67/3.93%)	2	-- --	No	V-0
P-B-MPN	P/N (2.36/3.71%)	0	-- --	No	V-0
P-C-MPN	P/N (2.97/3.11%)	0	-- --	No	V-0
DICY Control	P/N (0.00/2.78%)	52	+	No	V-2
P-A-DICY	P /N (1.86/3.36%)	0	-- --	No	V-0
P-B-DICY	P /N (2.61/3.14%)	0	-- --	No	V-0
P-C-DICY	P /N(3.26/2.96%)	0	-- --	No	V-0
TBBA/PN	Br (17.72%)	1	++	Yes	V-0
BHPP/PN	P (4.27%)	0	-- --	No	V-0

* ++: heavy; +: slightly; --: scarcely; -- -: no fume.

The data in Tables 1 and 2 show that the cured epoxy resins prepared from the ODOPM-BPA advanced epoxy resins of the present invention have excellent flame retardant properties in comparison with the conventional cured epoxy resins prepared from BPA advanced epoxy resins, especially no fume and dripping occur in the combustion test, and thus is very suitable for the printed circuit board applications.

Curing of epoxy resins with the phosphorus-containing hardeners and nitrogen-phosphorus-containing hardeners

i). Using P-1 to P-16 hardeners

Examples 1-16:

- 5 Cured epoxy resins were prepared from a cresol formaldehyde novolac epoxy resin (CNE) with the hardeners P-1 to P-16 prepared in Examples 1 to 16 in an equivalent ratio of epoxide : active hydrogen = 1:1 and with 0.2 wt% of triphenylphosphine as a curing accelerator. The mixture was grounded into fine powders to give thermosettable epoxy resin powders.
- 10 The resin powders were cured in a mold at 150°C and 50 kg/cm² for a period of one hour and then at 170°C for two hours and further postcured at 200°C for three hours to obtain cured specimens.

Control Example 1:

- 15 The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by phenol formaldehyde novolac resin (PN) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

20 Control Example 2:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by tetrabromobisphenol A (TBBA) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

Control Example 3:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by bis(3-hydroxyphenyl) phenyl phosphate (BHPP) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

Control Example 4:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by dicyandiamide (DICY) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

Control Example 5:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by melamine (MA) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

Control Example 6:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by bisphenol A (BPA) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

Control Example 7:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by
diaminodiphenylmethane (DDM) to cure the cresol formaldehyde novolac
5 epoxy resin (CNE) in the curing reaction.

Control Example 8:

The procedures of Example 1 were repeated except that ODOPM-BPA-A (P-1-A) used in Example 1 was replaced by diaminodiphenyl sulfone
10 (DDS) to cure the cresol formaldehyde novolac epoxy resin (CNE) in the curing reaction.

The dynamic mechanical analysis (DMA) properties of the resulting cured epoxy resins are shown in Table 3; the thermogravimetric analysis
15 data thereof are shown in Table 4; and the flame-retardant properties thereof are shown in Table 5.

Table 3 dynamic mechanical analysis (DMA) properties

Specimens	Hardeners	Glass transition temperature (T _g , °C)	Flexural strength at 50°C dyne/cm
Example 1	P-1	154	6.9
Example 2	P-2	142	7.3
Example 3	P-3	232	7.8
Example 4	P-4	186	7.1
Example 5	P-5	243	8.3
Example 6	P-6	202	7.4
Example 7	P-7	226	8.1
Example 8	P-8	178	7.2
Example 9	P-9	208	8.1
Example 10	P-10	186	7.1
Example 11	P-11	223	8.5
Example 12	P-12	189	7.8
Example 13	P-13	224	8.3
Example 14	P-14	181	7.2
Example 15	P-15	225	8.3
Example 16	P-16	187	7.5
Control Ex. 1	PN	176	7.2
Control Ex. 2	TBBA	120	6.1
Control Ex. 3	BHPP	125	6.8
Control Ex. 4	DICY	243	8.1
Control Ex. 5	MA	211	8.1
Control Ex. 6	BPA	150	6.8
Control Ex. 7	DDM	238	8.5
Control Ex. 8	DDS	242	8.7

Table 4 TGA data

Specimens	Hardener	Td 10% °C	Maximum thermal degradation temperature °C	Char yield (%) at 700°C
Example 1	P-1	383	413	32
Example 2	P-2	471	405	31
Example 3	P-3	373	398	42
Example 4	P-4	371	395	39
Example 5	P-5	387	401	40
Example 6	P-6	381	401	38
Example 7	P-7	387	421	37
Example 8	P-8	385	413	34
Example 9	P-9	387	421	42
Example 10	P-10	381	403	40
Example 11	P-11	395	429	38
Example 12	P-12	389	403	36
Example 13	P-13	391	411	38
Example 14	P-14	385	403	35
Example 15	P-15	395	429	42
Example 16	P-16	383	413	39
Control Ex. 1	PN	427	473	29
Control Ex. 2	TBBA	387	407	34
Control Ex. 3	BHPP	393	409	37
Control Ex. 4	DICY	418	468	12
Control Ex. 5	MA	395	441	12
Control Ex. 6	BPA	417	446	15
Control Ex. 7	DDM	413	422	30
Control Ex. 8	DDS	417	438	28

Table 5 Flame retardant properties (UL-94 test)

Specimens	Hardener	Content of P, N or Br	Burning time (Sec)	Drip	Fume	Classification
Example 1	P-1	P (3.62)	0	No	No	V-0
Example 2	P-2	P (3.54)	0	No	No	V-0
Example 3	P-3	P/N (3.75/3.39)	0	No	No	V-0
Example 4	P-4	P/N (3.67/3.31)	0	No	No	V-0
Example 5	P-5	P/N (3.54/3.19)	0	No	No	V-0
Example 6	P-6	P/N (3.47/3.13)	0	No	No	V-0
Example 7	P-7	P/N (2.29/6.20)	0	No	No	V-0
Example 8	P-8	P/N (2.25/6.11)	0	No	No	V-0
Example 9	P-9	P/N (3.38/6.09)	0	No	Yes	V-0
Example 10	P-10	P/N (3.32/6.01)	0	No	No	V-0
Example 11	P-11	P/N (2.38/4.30)	0	No	No	V-0
Example 12	P-12	P/N (2.35/4.24)	0	No	No	V-0
Example 13	P-13	P/N (2.31/6.27)	0	No	No	V-0
Example 14	P-14	P/N (2.30/6.25)	0	No	No	V-0
Example 15	P-15	P/N (3.44/6.22)	0	No	No	V-0
Example 16	P-16	P/N (3.43/6.19)	0	No	No	V-0
Control Ex. 1	PN	0	86	Yes	No	V-2
Control Ex. 2	TBBA	Br (21.19)	0	Yes	Yes	V-0
Control Ex. 3	BHPP	P (4.20)	0	No	No	V-0
Control Ex. 4	DICY	N (6.32)	46	Yes	Yes	V-2
Control Ex. 5	MA	N (6.31)	32	No	Yes	V-2
Control Ex. 6	BPA	0	91	Yes	Yes	V-2
Control Ex. 7	DDM	N (2.81)	83	Yes	Yes	V-2
Control Ex. 8	DDS	N (2.67)	78	Yes	Yes	V-2

It can be seen from Table 3 that the cured epoxy resins of the present invention have glass transition temperatures (T_g) about 60°C higher than

that of the epoxy resin cured with the conventional flame-retardant TBBA hardener. The data in Table 4 show that the cured epoxy resins of the present invention have a better thermal stability and higher char yield than those of the conventional epoxy resin cured by flame-retardant TBBA.

- 5 The data in Table 5 indicate that the cured epoxy resins of the present invention have excellent flame retardant properties, especially no fume and dripping occur in the combustion test, and thus is very suitable for use in the semiconductor encapsulation applications. The flame-retardant hardeners containing the phosphorus-containing rigid groups disclosed in
- 10 the present invention can be used to prepare flame-retardant cured epoxy resins having improved thermal properties and flame-retardancy, as shown in Tables 3 to 5. The nitrogen and phosphorus elements contained in the hardeners of the present invention have a synergistic effect in flame-retardancy of the cured epoxy resin.

15

ii). Using phosphorus-containing BPA hardener (P-1-A) prepared in Preparation Example 1-A

- Various amounts of the hardener ODOPM-BPA-A (P-I-A) were separately mixed with bisphenol (BPA) to form a mixed curing agent for
- 20 cresol formaldehyde novolac epoxy resin (CNE) to determine the flame-retardant effect of phosphorus. The mixed curing agents consisting of P-1-A/BPA in various weight ratios (0/100, 25/75, 50/50, 75/25, and 100/0) were prepared. Triphenyl phosphine (Ph_3P) powder was used as a curing accelerator. The CNE was mixed with the above mixed curing agents and

0.2 wt% Ph_3P in a mill at 25°C to give thermosettable epoxy resin powders, wherein the equivalent ratio of epoxide group to hydroxyl group is 1:1. The resin powders were cured in a mould at 150°C and 50 kg/cm^2 for a period of one hour and then at 170°C for two hours and further postcured at
5 200°C for three hours to obtain cured specimens.

For comparison, various weight ratios of tetrabromobisphenol A (TBBA) and PN (25/75, 75/25, 100/0) were also used as a curing agent to prepare the cured specimens as above.

The cured specimens were subjected to the thermogravimetric
10 analysis and the UL-94 test. The results are shown in Table 6 and Table 7.

It can be seen from Table 6 that the T_g values of the phosphorus-containing cured epoxy resin specimens of the present invention (P-1-A/BPA) are about 30°C higher than those of the conventional bromine-
15 containing cured epoxy resin specimens. Furthermore, the phosphorus-containing cured epoxy resin specimens of the present invention exhibit significantly higher thermal degradation temperatures and higher char yields in comparison with the conventional bromine-containing cured epoxy resin specimens.

20 The data in Table 7 show that 1.13% phosphorus content of the phosphorus-containing cured epoxy resin of the present invention can produce substantially the same flame-retardant effect as 11.92% bromine content of the conventional bromine-containing cured epoxy resin. In addition, the phosphorus-containing cured epoxy resin specimens of the

present invention generate much less fumes in the combustion test.

The results shown in Tables 6 and 7 indicate that the phosphorus-containing cured epoxy resin of the present invention is very suitable for semiconductor encapsulation applications.

Table 6 TGA data

Specimens	Content of flame-retardant element	T _g (°C)	Temperature of 5 wt% loss, °C		Temperature of 10 wt% loss, °C		Rapid rate Tr (°C)				Char yield at 700°C, (%)	
			Air	N ₂	Air	N ₂	Step 1 Air	Step 1 N ₂	Step 2 Air	Step 2 N ₂	Air	N ₂
	P (%)											
P-1-A/BPA (0/100)	0	150	407	397	421	417	436	446	—	—	4	15
P-1-A/BPA (25/75)	1.13	142	397	387	413	413	435	440	—	—	8	21
P-1-A/BPA (50/50)	2.08	146	383	381	405	401	425	435	620	—	15	24
P-1-A/BPA (75/25)	2.91	151	363	367	393	393	416	421	610	—	21	27
P-1-A/BPA (100/0)	3.62	154	357	353	393	383	412	413	561	567	28	32
	Br (%)											
TBBA/PN (25/75)	6.39	130	371	381	379	383	385	393	—	—	5	16
TBBA/PN (50/50)	11.92	127	369	377	379	387	385	395	—	—	7	17
TBBA/PN (75/25)	16.82	124	363	367	369	391	387	401	—	—	10	23
TBBA/PN (100/0)	21.29	121	367	369	371	395	391	407	—	—	12	25

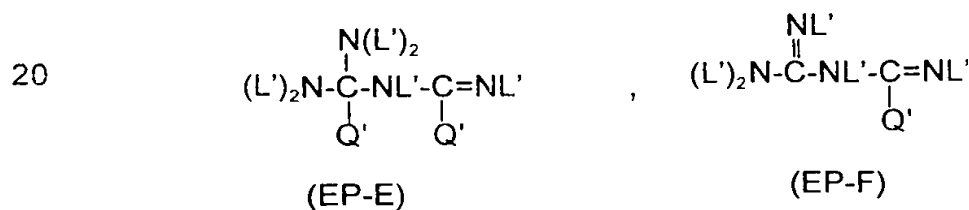
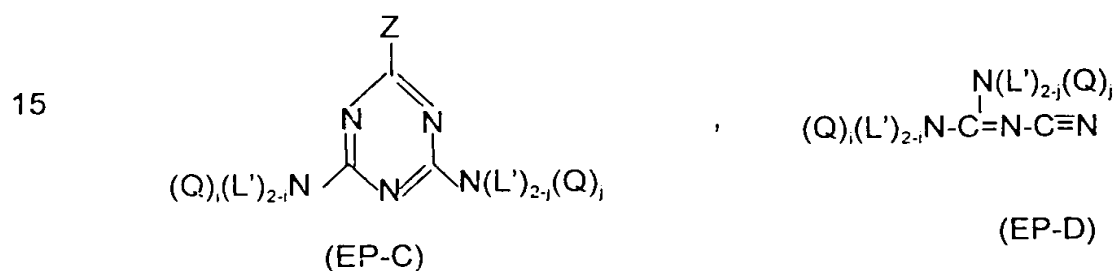
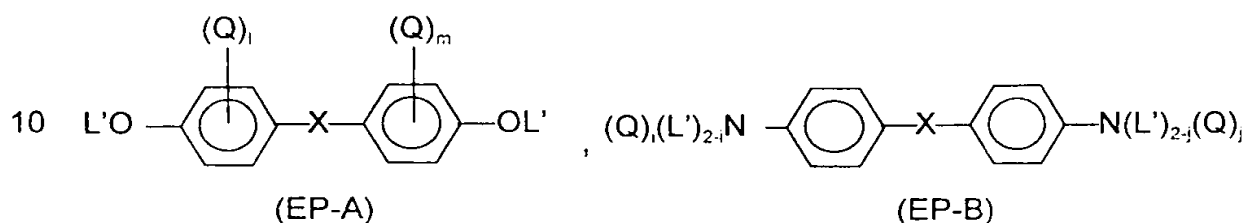
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Table 7 Flame retardant properties (UL-94 test)

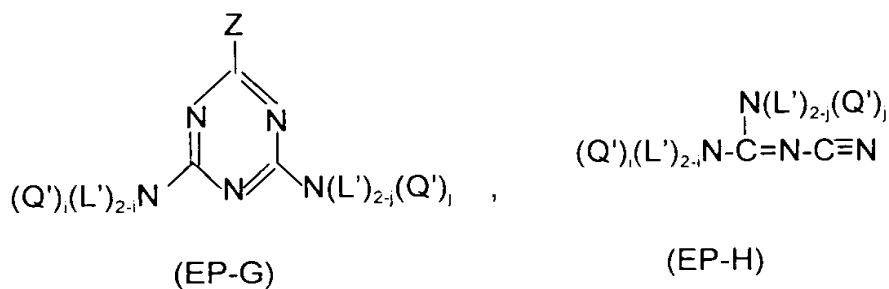
Specimens		Burning	Fume*	Drip	Classification
P-1-A/BPA	P%	time (Sec)			
0/100	0	91	+	Yes	V-2
25/75	1.13	8	+	No	V-0
50/50	2.08	0	-- --	No	V-0
75/25	2.91	0	-- --	No	V-0
100/0	3.92	0	-- --	No	V-0
TBBA/PN	Br%				
25/75	6.39	20	++	Yes	V-1
50/50	11.92	6	++	Yes	V-0
75/25	16.82	0	+	No	V-0
100/0	21.19	0	--	No	V-0

* ++: heavy; +: slightly; --: scarcely; -- -: no fume.

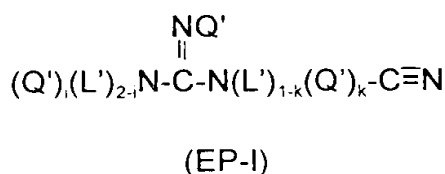
The phosphorus-containing compounds (A)-(I) of the present invention have an active hydrogen, and thus can be used as a starting material for the preparation of flame-retardant epoxy resins by reacting with epihalohydrin under alkaline condition as disclosed in US patent No. 4,499,255. The details of this US patent are incorporated herein by reference. The flame-retardant epoxy resins so prepared will have one of the formulas (EP-A) to (EP-I) as follows:



25

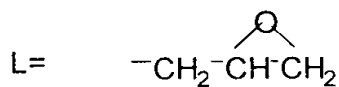


5



10

wherein l, m, i, j, k, Z, X, Q and Q' are defined as above; and L' is hydrogen or



, provided that at least two L' are L.

15 Preferably, the flame-retardant epoxy resins (EP-A) to (EP-I) are prepared from the preferred phosphorus-containing compounds of the present invention.

Preferably, the flame retardant epoxy resin has the formula (EP-A).

Preferably, the flame retardant epoxy resin has the formula (EP-B).

20 The present invention further synthesizes a phosphorus-containing flame-retardant cured epoxy resin by curing the epoxy resin selected from (EP-A) to (EP-I) with the conventional curing agent for the epoxy resin, which preferably is selected from the group consisting of pherol-

formaldehyde novolac resin, dicyandiamide and hexahydrophthalic anhydride. Preferably, the curing reaction is carried out at a temperature higher than 150°C and with stoichiometric amount of the curing agent (hardener). More preferably, the curing reaction is carried out in the presence of a curing promoter such as triphenylphosphine, and in an amount of 0.01~10.0 parts by weight of the curing promoter per 100 parts by weight of the epoxy resin. The phosphorus-containing flame-retardant cured epoxy resin of the present invention is suitable for use in making a flame-retardant printed circuit board as a matrix resin and in semiconductor encapsulations.

Preparation of phosphorus-containing epoxy resins and cured epoxy resins

i). Preparation of phosphorus-containing epoxy resins

Example 17 (P-D):

To a reaction vessel equipped with a temperature controller, a mechanical stirrer, a reflux condenser, a dean stark trap and a vacuum system was added 91.2 g (0.4 equivalent) of 2-(6-oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl) methyl – bisphenol-A (ODOPM-BPA-A) (P-1-A), 185 g (2 equivalents) of epichlorohydrin (EPI), and 54 g of 1-methoxy-2-hydroxy propane as a solvent. After stirring at room temperature and atmospheric pressure to thoroughly mix the contents, the temperature was raised to 65°C and the pressure was reduced to 160 mm Hg absolute. To the resultant solution was continuously added 32 g of

50% aqueous sodium hydroxide solution at a constant rate over a period of 1 hour. During the addition of the sodium hydroxide, the water was removed by codistilling with epichlorohydrin and solvent. The distillate was condensed and introduced into the dean stark trap, wherein two
5 distinct phases, an aqueous phase (top) and an organic epichlorohydrin-solvent phase (bottom) were formed. The aqueous phase was removed continuously and disregarded. The organic phase was continuously returned to the reactor. After completion of the sodium hydroxide addition, the reaction mixture was maintained at a temperature of 65°C and a
10 pressure of about 160 mm Hg absolute for an additional 30 minutes. The reaction mixture was washed with deionized water two or three times to remove salt after cooling, and subsequently distilled to remove residual EPI resulting in a phosphorus-containing epoxy resin (P-D) having an epoxide equivalent weight (EEW) of 298-301.

15

Example 18 (P-E):

The procedures of Example 17 were repeated except that 82.8 g (0.4 equivalent) 2-(6-oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl) methyl - 4,4'-biphenol-A (ODOPM-BP) was used to replace ODOPM-BPA-A (P-1-A).
20 The resultant phosphorus-containing epoxy resin (P-E) had an EEW of 279-281.

Example 19 (P-F):

The procedures of Example 17 were repeated except that 95.6 g (0.4

equivalent) 2-(6-oxid-6H-dibenz<c,e><1,2>oxa-phosphorin-6-yl) methyl -
4,4'- sulfonyl diphenol-A (ODOPM-SDP) was used to replace ODOPM-
BPA-A (P-1-A). The resultant phosphorus-containing epoxy resin (P-F)
had an EEW of 315-319.

5

Control Example 9 (BPA-9):

The procedures of Example 17 were repeated except that 45.6 g (0.4
equivalent) bisphenol-A (BPA) was used to replace ODOPM-BPA-A (P-1-A).
The resultant phosphorus-containing epoxy resin (BPA-9) had an EEW of
10 181-185.

Control Example 10 (BP-10):

The procedures of Example 17 were repeated except that 37.2 g (0.4
equivalent) 4,4'-biphenol-A (BP) was used to replace ODOPM-BPA-A (P-1-
15 A). The resultant phosphorus-containing epoxy resin (BP-10) had an
EEW of 159-162.

Control Example 11 (SDP-11):

The procedures of Example 17 were repeated except that 50 g (0.4
20 equivalent) 4,4'-sulfonyl diphenol (SDP) was used to replace ODOPM-
BPA-A (P-1-A). The resultant phosphorus-containing epoxy resin (SDP-
11) had an EEW of 191-195.

Control Example 12 (TBBA-12):

The procedures of Example 17 were repeated except that 108.8 g (0.4 equivalent) tetrabromobisphenol A (TBBA) was used to replace ODOPM-BPA-A (P-1-A). The resultant phosphorus-containing epoxy resin (TBBA-12) had an EEW of 356-359.

5

Control Example 13 (BHPP-13):

The procedures of Example 17 were repeated except that 71.6 g (0.4 equivalent) bis(3-hydroxyphenyl) phenyl phosphate (BHPP) was used to replace ODOPM-BPA-A (P-1-A). The resultant phosphorus-containing
10 epoxy resin (BHPP-13) had an EEW of 253-256.

ii). Preparation of a cured epoxy resin from a phosphorus-containing epoxy resin

Cured epoxy resins were prepared from the epoxy resins prepared in
15 Examples 17-19 and Control Examples 9-13 with phenol-formaldehyde novolac resin (PN) as a curing agent.

The epoxy resin was mixed with the curing agent (1:1 equivalent ratio) at 150°C with stirring, and the well mixed molten mixture was poured into a hot aluminum mould, cured in an oven at 170°C for one hour, and then
20 postcured at 200°C for two hours.

The dynamic mechanical analysis (DMA) properties of the resulting cured epoxy resins are shown in Table 8; the thermogravimetric analysis data thereof are shown in Table 9; and the flame-retardant properties thereof are shown in Table 10.

Table 8 dynamic mechanical analysis (DMA) properties

Specimens	Epoxy resins	Glass transition temperature (T _g , °C)	Flexural strength at 50°C dyne/cm
Example 17	P-D	132	6.5
Example 18	P-E	127	6.9
Example 19	P-F	189	8.1
Control Ex. 9	BPA-9	127	6.3
Control Ex. 10	BP-10	121	6.5
Control Ex. 11	SDP-11	187	8.3
Control Ex. 12	TBBA-12	117	6.3
Control Ex. 13	BHPP-13	105	6.9

Table 9 TGA data

Specimens	Epoxy resins	Td 10% °C	Maximum thermal degradation temperature °C	Char yield (%) at 700°C
Example 17	P-D	397	427	42
Example 18	P-E	401	441	44
Example 19	P-F	381	398	38
Control Ex. 9	BPA-9	417	442	26
Control Ex. 10	BP-10	425	456	24
Control Ex. 11	SDP-11	393	409	18
Control Ex. 12	TBBA-12	409	418	35
Control Ex. 13	BHPP-13	377	393	38

Table 10 Flame retardant properties (UL-94 test)

Specimens	Epoxy resins	Content of P or Br	Burning time (Sec)	Drip	Fume	Classification
Example 17	P-D	P (4.04)	0	No	No	V-0
Example 18	P-E	P (4.29)	0	No	No	V-0
Example 19	P-F	P (3.88)	0	No	No	V-0
Control Ex. 9	BPA-9	0	81	No	Slightly	V-2
Control Ex. 10	BP-10	0	93	No	Slightly	V-2
Control Ex. 11	SDP-11	0	72	Yes	Yes	V-2
Control Ex. 12	TBBA-12	Br (37.7)	0	No	No	V-0
Control Ex. 13	BHPP-13	P (4.64)	0	No	No	V-0

It can be seen from Table 8 that the cured epoxy resins of the present invention have glass transition temperatures (T_g) about higher than those of the conventional bisphenol-A cured epoxy resin and the conventional flame-retardant TBBA cured epoxy resin. The data in Table 9 show that the cured epoxy resins of the present invention have a better thermal stability and higher char yield than those of the conventional flame-retardant TBBA epoxy resin cured by phenol-formaldehyde novolac resin (PN). The data in Table 10 indicate that the cured epoxy resins of the present invention have excellent flame retardant properties, especially no fume and dripping occur in the combustion test, and thus is very suitable for use in the semiconductor encapsulation applications. The flame-retardant epoxy resins containing the phosphorus-containing rigid group (ODOPM) bonded to BPA, BP and SDP disclosed in the present invention can be used to prepare flame-retardant cured epoxy resins having improved thermal properties and flame-retardancy, as shown in Tables 8 to

10.

The presently disclosed embodiments are therefore considered in all respects to be illustrative and not restrictive. The scope of the invention is indicated by the appended claims rather than the foregoing description, and all changes that come within the meaning and range of equivalents thereof are intended to be embraced therein.

What is claimed is: